

R&D SERVICES

BEYOND WAFER
PROBE CARDS



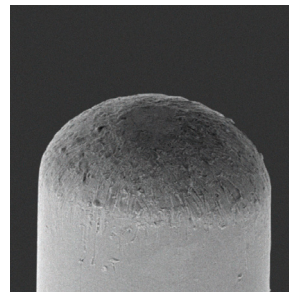
FEINMETALL
Contact Technologies



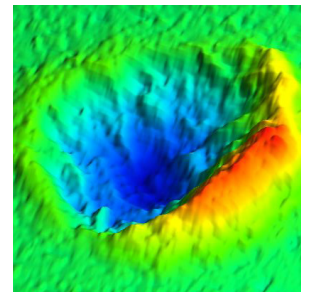


Performance Study

- C_{Res} measurements when probing on customer or blank wafer with FM-technologies
- Probing with different parameters such as temperature, overtravel, multi TDs on same pad/bump
- Analysis on lateral scrub dimensions with wafer microscope
- Scrub mark-depth and pile-up analysis with atomic force microscope
- Optional: Pad crack analysis



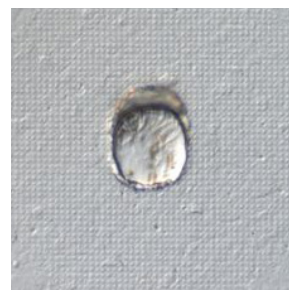
Round Tip Shape



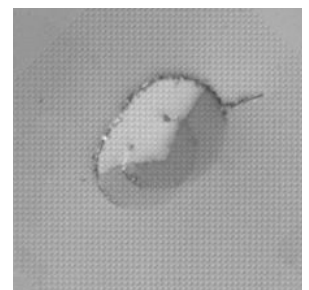
AFM-Analysis

Pad Crack Analysis

- Probing with different parameters such as temperature, overtravel, multi TDs on same pad/bump
- Analysis on lateral scrub dimensions with wafer microscope
- Etching off pad material
- Pad crack analysis with wafer microscope
- Optional: Scrub mark-depth and pile-up analysis with atomic force microscope before etching



Scrub Mark after Probing

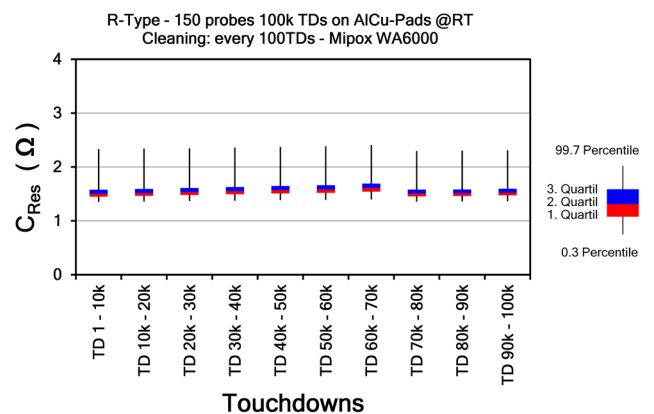


Pad Crack after Etching



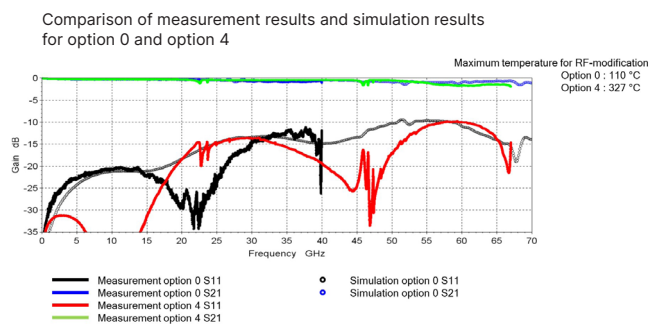
Lifetime Study

- C_{Res} measurements when probing on customer or blank wafer with FM-technologies
- Probing with different parameters such as temperature, overtravel, multi TDs on same pad/bump
- Analysis on lateral scrub marks dimensions with wafer microscope
- Optional: Customized cleaning recipe design (with preferred cleaning material)



RF Analysis

- Offering encrypted CAD (Protected project) data for the purpose of high-frequency simulation
- RF-Simulation data and information on lumped devices as well as information on power and signal integrity can be created on request



FM Services at a Glance

	Encrypted CAD (Protected project) data	RF Simulation	Lumped devices	Power integrity	Signal integrity
Data packages	✓	Optional	Optional	Optional	Optional

	Performance Study	Pad Crack Analysis	Lifetime Study
C _{Res} measurements	✓	–	✓
Probing with different parameters	✓	✓	✓
Analysis on lateral scrub dimensions	✓	✓	✓
Scrub-depth and pile-up analysis	✓	Optional	–
Pad Crack analysis	Optional	✓	–
Customized cleaning recipe	–	–	Optional

We Offer...

Years of experience and expertise in the wafer probing business enable us to find the right contact solution for every application and to guarantee a fail-safe worldwide test operation.

In addition to our broad portfolio we offer specific feasibility studies with three different main focuses to find the optimal probing solution for your product.

Contact Us Today

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Customer Oriented Probe Card Service - All Over the Globe

For your tailored support we offer various levels of service agreements, combining some important advantages:

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- Guaranteed turnaround times
- Custom-tailored solution from small repairs to complete repair shop management
- High competence and deep understanding of customer needs



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